

Certificate of Participation

This is certified that

Oo Cheng Hong

has attended the

**International Conference on Electronic and Advanced Materials 2021
(ICEAM 2021)
2nd November 2021**

organized by

**Center of Excellence Geopolymer & Green Technology (CEGeoGTech)
Tin Solder Technology Research Group Malaysia (TSTRG)
Electronic Packaging Research Society (EPRS)**



**Assoc. Prof. Ir. Dr. Shayfull Zamree Abd Rahim
Leader**

**Center of Excellence Geopolymer & Green Technology (CEGeoGTech)
Universiti Malaysia Perlis (UniMAP)**

